

**Notice of References Cited**

Application/Control No.

09/903,792

Applicant(s)/Patent Under  
Reexamination  
NAKATA ET AL.

Examiner

Kripa Sagar

Art Unit

1756

Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,346,564	02-2002	Kubota et al.	524/403
	B	US-2002/0076657	06-2002	Towata, Shuichi	430/322
	C	US-2002/0094382	07-2002	Imai et al.	427/282
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Thick Film Processes"; in Hybrid Microcircuit Technology Handbook, (Noyes, 1998), ch.4; pp. 104-171.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.